

ABSTRACT

An electronic device comprises a substrate with a trench having a lower portion and a top portion. The lower portion of the trench is filled with a cured spin-on compound, while the top portion is filled with a chemical vapor-deposited compound. Preferably, the chemical vapor-deposited compound has a surface that is substantially coplanar with the surface of the substrate. Particularly preferred methods of fabricating such devices include a step in which a trench is formed in the substrate, and in which a first compound is deposited in the trench by spin-on deposition. The first compound is partially removed from the trench to a level below the surface of the substrate, and in a further step, a second compound is deposited onto the upper surface of the first compound by chemical vapor deposition.